Low-Power, High-Performance Architecture of the PWRficient Processor Family

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Acknowledgement



THE ARCHITECTURE, DESIGN, AND IMPLEMENTATION OF THE PWRFICIENT PROCESSOR FAMILY ARE THE OUTCOME OF THE UNTIRING EFFORTS OF THE ENTIRE TEAM AT P.A. SEMI, INC.

Outline



- Design paradigm
- ► Family
- Core
- Performance and power
- **Summary**

Low-Power Design Paradigm

Design goal — 970-class performance at less than 7 watts per core Power dissipation is a primary consideration at all levels

- Circuit and Process
 - Voltage/frequency scaling
 - Multiple power planes for optimal voltage selection per region
- Microarchitecture and Logic
 - Clock gating to reduce power of idle circuits
 - Active and pre-charge standby modes in external DRAM array
 - Sizing and hierarchy of cache structures
- Architecture
 - Integration to reduce I/O interface power
 - ▶ Internal and external power-saving modes CPU, memory controller, PCIe
- Verification
 - Monitor power consumption against budget throughout the design process
- Software
 - Power management of I/O devices and CPU

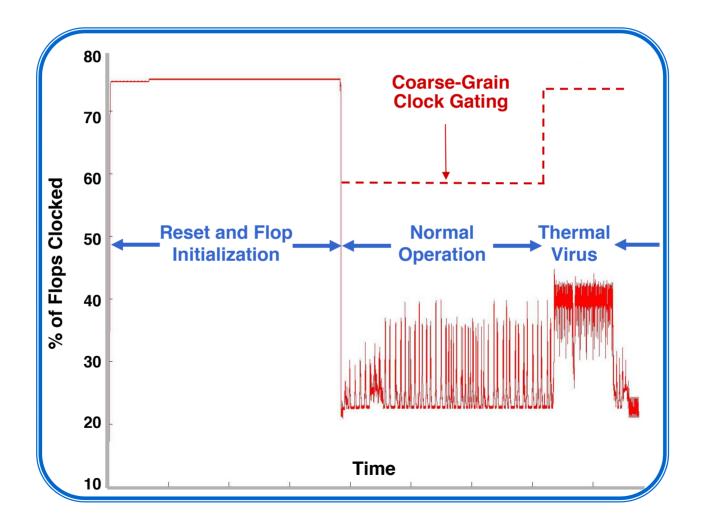
Power-Influenced μ /Architectural Choices

Extensive fine-grained clock gating used throughout core and SOC

- If a function can be performed sequentially without performance loss, why build power-hungry parallel mechanisms?
- ► The smaller, the better
 - Design employs smaller subsections that are powered up for frequent accesses
 - Much attention to clocking only those elements that are performing work
- Each major block's design criteria included goals for power in addition to the traditional area, complexity & timing budgets
 - Energy per memory access at each level of cache vs. DRAM
 - Leakage, voltage, and execution frequency
 - Overall execution time saving

Speculation has to be effective or it becomes a power sink

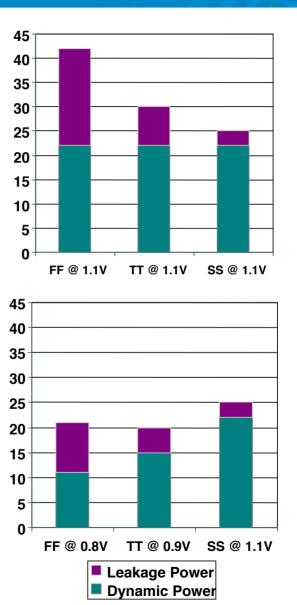
Fine-Grain Clock Gating Reduces Dynamic Power



Device-Specific V_{dd} Reduces Static and Dynamic Power

Conventional approach

- Operate at 1.1V across entire process range
- Fast parts tend to be very leaky



P.A. Semi approach

- Operate at device-specific optimal V_{dd}
- Partition power plane for optimal voltage selection per region
- Enables full process range for power yield

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PWRficient Family



PWRficient Family



► PA6T core — the CPU

- Power Architecture compliant, 64-bit, high-performance FPU and VMX
- ► 7W @ 2GHz worst-case power dissipation

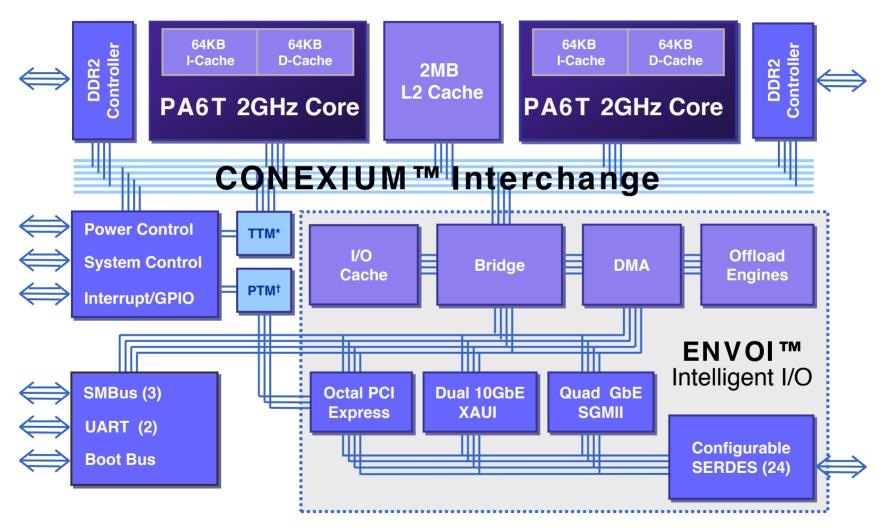
► CONEXIUM[™] — the on-chip coherent interconnect

- Scalable cross-bar interconnect
- ► 1-8 SMP cores
- 1 or 2 L2 caches, sized 512KB-8MB
- 1–4 64-bit DDR2 memory controllers

► ENVOI[™] — the I/O system

- SERDES I/O—PCI Express[®], XAUI, SGMII
- Offload engines—TCP/IP, iSCSI, cryptography, and RAID
- Support I/O—Boot bus, UARTs, SMBus, GPIOs

PWRficient PA6T-1682M Block Diagram



*Transaction trace memory †Peripheral trace memory

The PA6T Core



PA6T Core Features

Fully compliant Power Architecture implementation

- Power Architecture version 2.04
- Full FPU and VMX SIMD capabilities
- ▶ 64-bit with 32-bit capability

Super-scalar, out-of-order design

- L1 instruction cache
 - Fetch four instructions per cycle into 64entry scheduler
 - Issue up to 3 per cycle into 6 functional units
- Branch predictors
- Strongly ordered memory model
 - Issue out of order, retire in order

Hypervisor and virtualization support

High-performance memory hierarchy @ 2GHz

- L1 data—32GB/s read or write
- L2 data—16GB/s read plus 16GB/s write
- DDR2-1067—16GB/s read or write
- 16 transactions in flight

CONEXIUM Interchange

- IG transactions per second
- ► 64GB/s peak data rate
- MOESI coherency protocol

PA6T Low-Power Features

Improved branch prediction

Minimize incorrect speculation to avoid wasting power

Efficient superscalar design

Index-based, out-of-order execution engine minimizes the use of CAMs and avoids unnecessary replays

Energy-efficient memory pipelines

- ► Hierarchical address translation to balance power consumption and performance
- Highly integrated memory pipeline that supports out-of-order execution and sequential consistency with minimal data movement

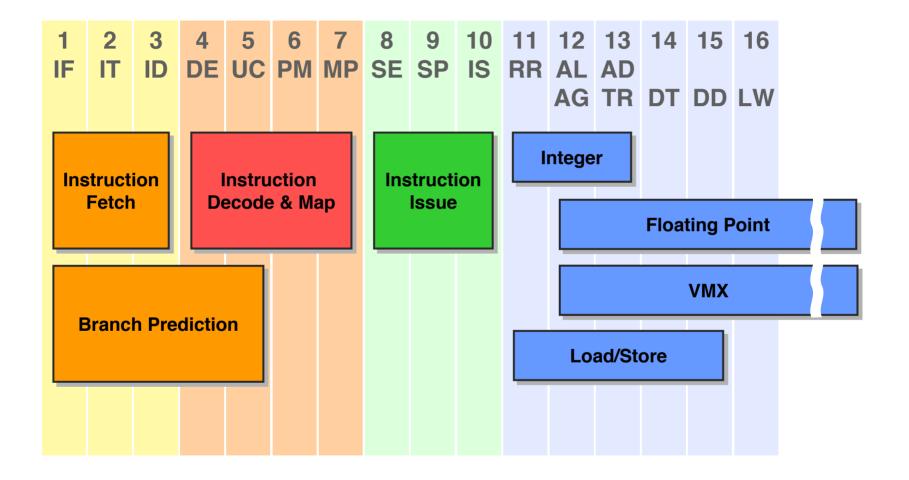
Coherent memory subsystem

Coherent memory subsystem designed for high throughput and low latency while minimizing the energy used per reference

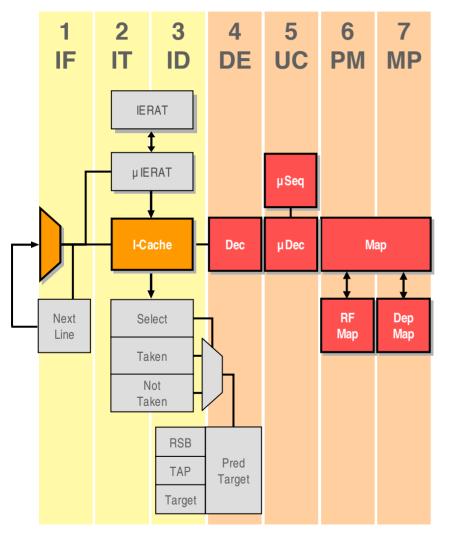
Extensive power-management capabilities

Doze, nap, and sleep power-down modes trade varying degrees of power savings with recovery time

Processor Pipeline



Front End



back to main diagram

► I-cache

- ► 64KB
- 2-way associative
- 2-cycle
- 4 instructions/fetch
- 4 fetches to CONEXIUM
- Next-line pre-fetch after a miss

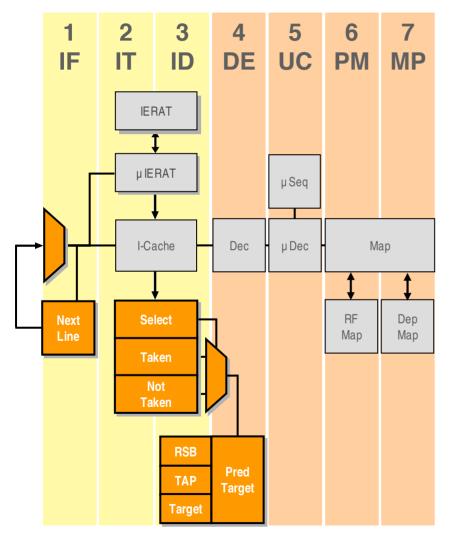
Instruction buffer

- 4 fetch groups (16 instructions)
- Decode
 - 4 µ ops/dispatch

Map

- 4 µ ops renamed/cycle
- 64 rename registers

Branch Processing



back to main diagram

Branch prediction

 0-cycle bubble: 16-entry next-fetch prediction

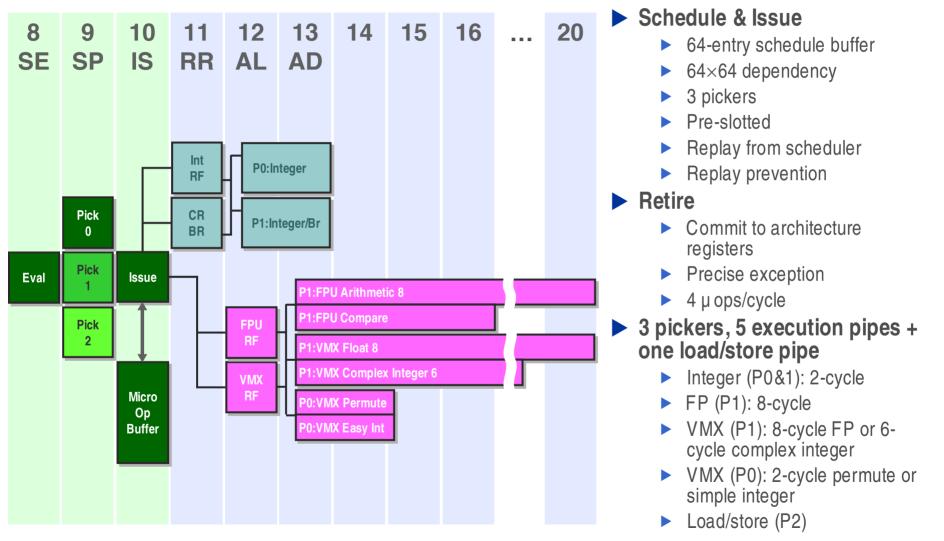
4-cycle bubble (taken prediction)

- Path: 16K bi-mode taken/not taken (4 predicted)
- 16-entry return stack
- 64-entry history-assisted target predictor
- IP-relative
- Early verification
- Branch execution
 - 2-cycle branch execution on integer P1

Branch misprediction

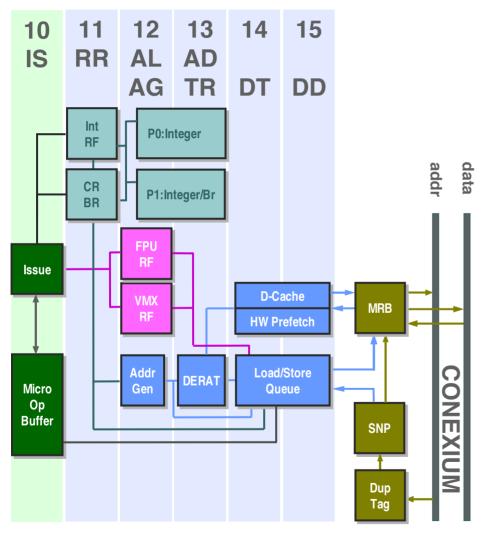
- 13-cycle path mispredict
- 13-cycle target mispredict

Scheduler and Execution Pipes



back to main diagram

Load/Store Processing



back to main diagram

► Latency — Load to Use

- L1 cache 4
- L2 cache 24
- ► Open page 100
- Closed page 120
- ► Remote L1 42

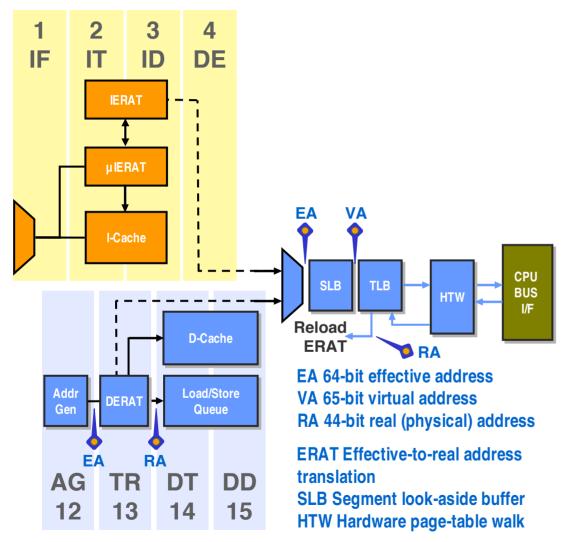
Loads and Stores

- Issued out of order
- Strongly-ordered stores

► 32-Entry Load/Store Queue

- Re-ordered for consistency
- Checking and retire
- Store-to-load forwarding
- 16 blocks in flight
- 12-entry hardware prefetcher

Address Translation



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I-address translation

D-address translation

4-entry direct µ IERAT

64-entry 2-way IERAT

128-entry 2-way DERAT

► SLB—64-entry fully-assoc

TLB—1024-entry 4-way

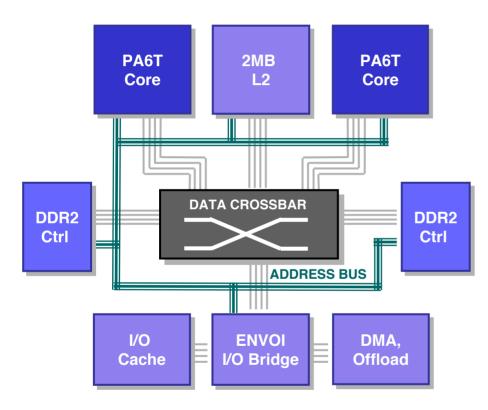
H/W Page table walk

4-walks in flight

Prefetch of next PTF

after a TLB miss

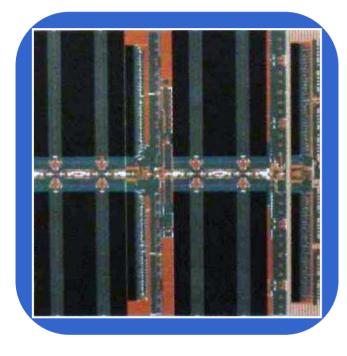
CONEXIUM Interchange



Transaction initiators: cores & I/O bridge

- All devices respond
- MOESI-style protocol
 - Minimize copy-back to memory and L2-cache to save power
- Address bus cycles at half the core frequency—1G address/sec
- Address arbitration enforces strong ordering
- Data connected as crossbar
 - Scales with number of agents
- Each port provides 16-byte dualsimplex connections

Memory Hierarchy



On-chip memories are power efficient

- RAM structures have low power density due to low inherent activity
- Only a few of many bit cells accessed per cycle
- On-chip RAMs save power by avoiding chip-to-chip bus structures
- Most on-chip memory is devoted to caches
 - Caches have diminishing (logarithmic) performance return vs. size

Power Saving Modes

Doze (entry time immediate, wakeup time immediate)

- Cores idle at reduced frequency; continue snooping on the bus
- Wake up immediately—no state reloading needed
- Nap (entry time 2–16µs*, wakeup time <0.5 ms)</p>
 - Core clock stopped and voltage lowered to reduce leakage
 - D-cache modified data is flushed by hardware
 - All architecture state is retained
 - SRAM remains power on, value retained
 - Branch predictors: state retained
 - TLB, I-cache: invalidate if snooped
- Sleep (entry time 2–16µs*, wakeup time <1 ms[†])
 - Core powered off (either or both cores)
 - D-cache modified data is flushed by hardware
 - Some architecture state must be saved by software
 - On wakeup, core goes through power-on-reset sequence

*Depends on number of modified L1 data cache lines †Wakeup time is dominated by power regulator restart time

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PWRficient Performance & Power



High Performance at Low Power Across a Range of Metrics

PWRficient 1682M PROVIDES MAINSTREAM PERFORMANCE AT LOW POWER

General-purpose computing

SPECint[®]2000 >1000 per core*

Floating-point performance

- SPECfp[®]2000 >2000 per core*
- Imaging
 - ► FFT 24 GFlops/sec (total)[†]

System bandwidth

- Sustained block copy
 - 10 Gigabytes/sec*
- ► High-speed SERDES I/O
 - 104Gbps aggregate peak bandwidth

Application offloads

- TCP/IP termination
 - ► > 20Gbps[§]
- Encryption
 - 10Gbps IPSec/SSL encryption and authentication[§]
 - 3,000 public-key handshakes/sec in software*
- Storage
 - 2.0GB/s RAID5 (data+parity)§

*Estimated max sustained performance at 2GHz

[†]75% of estimated max sustained performance at 2GHz, 1D single-precision FFT with 2K elements

§Estimated peak performance at 2GHz

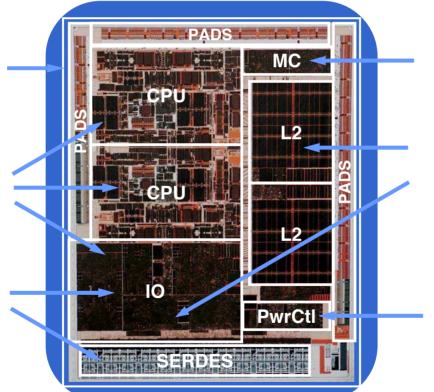
Power Efficient

POWER IS FIRST-ORDER DESIGN PRINCIPLE

> 15,000 gated clocks

Separate power rails for cores, I/O pads

Turn off unused I/Os

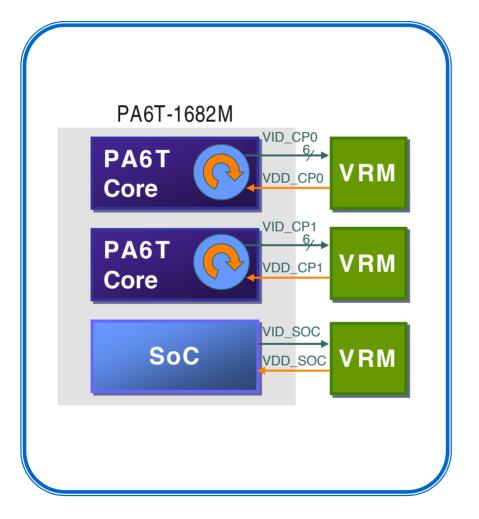


MC optimizes DRAM power

L2 cache and I/O are coherent with core off

Dynamic power-control hardware and software voltage/frequency management

PA6T-1682M Projected Power Dissipation



Projected power assuming full power-regulation scheme

- Independent per-core VRM
 - Dynamic control loop based on frequency and operating conditions
- VRM for SOC
 - Static control

	Max Freq	Тур	Max
PA6T core only	2.0GHz	4W	7W
PA6T-1682M-FCN	2.0GHz	17W	25W
PA6T-1682M-FCG	1.5GHz	8W	15W
PA6T-1682M-FCD	1.0GHz	6W	10W
I/O coherent nap			2W*

*PA6T-1682M-FCN nap power may be higher

Summary

- Power-aware design from ground up to maximize performance/Watt
- Modular design supports rapid family deployment
- Interesting convergence of needs across a wide range of design points
 - ► Networking, telecom, servers, mil/aero, imaging
- Performance and power enable wide range of applications

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